



Material Content Data Sheet



Sales Product Name		BSC014NE2LSI		Issued		23. January 2018		
MA#		MA001648560						
Package		PG-TDSON-8-7		Weight*		118.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.732	0.62	0.62	6178	6178
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		319	
wire	non noble metal	copper	7440-50-8	37.762	31.85	31.89	318495	318910
	noble metal	gold	7440-57-5	0.045	0.04	0.04	379	379
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		737	
	plastics	epoxy resin	-	6.200	5.23		52292	
	inorganic material	silicondioxide	60676-86-0	37.374	31.52	36.82	315223	368252
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12244	12244
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1396	1396
solder	non noble metal	tin	7440-31-5	0.021	0.02		176	
	noble metal	silver	7440-22-4	0.026	0.02		219	
	non noble metal	lead	7439-92-1	0.994	0.84	0.88	8385	8780
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.55	9.56	95477	95602
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		188	
	non noble metal	copper	7440-50-8	22.292	18.80	18.83	188015	188259
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com